# HZ0805E601R-10

## UNCONTROLLED DOCUMENT

#### PHYSICAL DIMENSIONS:

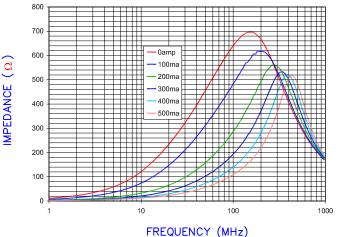
A 2.00 [.079] ± 0.20 [.008]

B 1.25 [.049] ± 0.20 [.008]

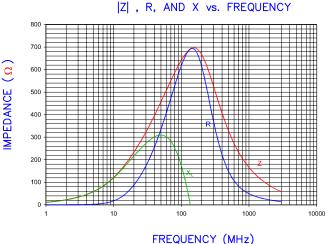
C 0.90 [.035] ± 0.20 [.008]

D 0.51 [.020] ± 0.25 [.010]

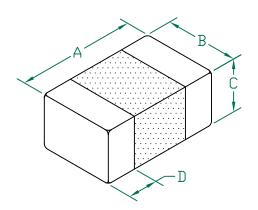
### Z vs FREQUENCY IMPEDANCE UNDER DC BIAS



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AGILENT E4991A RF Impedance/Material Analyzer HP 16194A Test Fixture. TEST REF. 3228





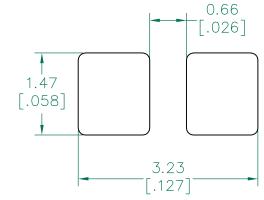
ELECTRICAL CHARACTERISTICS:										
Z @ 100M ( Ω )	1Hz	DCR $\left(\begin{array}{c}\Omega\end{array} ight)$	Rated Current							
Nominal	600									
Minimum	450									
Maximum	750	0.300	500 mA							

NOTES: UNLESS OTHERWISE SPECIFIED

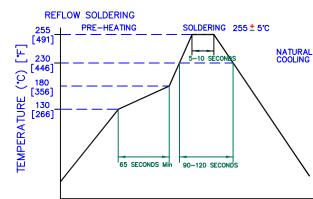
- 1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 4000 PCS/REEL, PAPER TAPE.
- 2. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 3. TERMINATION FINISH IS 100% TIN.
- 4. OPERATING TEMP. RANGE: -40°C~+125°C (INCLUDING SELF-HEATING)

#### LAND PATTERNS FOR REFLOW SOLDERING

RECOMMENDED SOLDERING CONDITIONS
FLOW SOLDERING



2002/95/EC



(For wave soldering, add 0.763 ([.030] to this dimension.)

DIMENSIONS ARE IN mm [INCHES].			This print is the property of Laird						
				Tech, and is loaned in confidence subject to return upon request a		╣▐▍▗▃▐ <u>▘</u> ▗▗█▘			
		with the understanding that no							
				copies shall be made without the written consent of Laird Tech. Al	┆╽╏	LQ			
Ε	ADD OPERATING TEMPERATURE UPDATE LAIRD LOGO AND REFLOW CURVE	08/05/13	QU	rights to design or invention are reserved.					
D	CHANGE SOLDERING TEMPERATURE	08/23/10	JUN	PROJECT/PART NUMBER:	REV	PART T		DRAWN BY:	
С	CHANGE TO PAPER TAPE	03/03/10	JUN	HZ0805E601R-10	5	CO-FIRE		JRK	
В	UPDATE COMPANY LOGO ADD ROHS	03/21/08	JRK	DATE: 03/01/04	CALE:	NTS	SHEET:		
Α	ORIGINAL DRAFT	03/01/04	JRK	CAD 4	T00L #		2	of 2	
REV	DESCRIPTION	DATE	INT	HZ0805E601R-10-E				01 2	